

93 U.S.S.N. 60/120,955, filed April 13, 1999, both of which are incorporated herein by reference.

Please amend the paragraph beginning on page 53, line 2, to read as follows:

94 FIGURES 26 through 28 are top plan views of integrated processing tools, shown generally at 1450, 1455, and 1500 that may be used to deposit a noble metal on the surface of a microelectronic workpiece, such as a semiconductor wafer. Processing tools 1450 and 1455 are each based on tool platforms developed by Semitool, Inc., of Kalispell, Montana. The processing tool platform of the tool 1450 is sold under the trademark LT-210™, the processing tool platform of the tool 1455 is sold under the trademark LT-210C™, and the processing tool 1500 is sold under the trademark EQUINOX™. The principal difference between the tools 1450, 1455 is in the footprints required for each. The platform on which tool 1455 is based has a smaller footprint than the platform on which tool 1450 is based. Additionally, the platform on which tool 1450 is based is modularized and may be readily expanded. Each of the processing tools 1450, 1455, and 1500 are computer programmable to implement user entered processing recipes.

In the Claims:

Amend Claim 15. All pending claims as thusly amended follow:

95 15. (Amended) A method for electroplating a noble metal into submicron features on a surface of a microelectronic workpiece, the method comprising the steps of:

bringing the surface of the workpiece that is to be plated into contact with an electroplating solution including ions and/or complexes of a noble metal that is to be plated on

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